2022 年度广东省科学技术奖公示表

（科技进步奖）

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| **项目名称** | **高密度高集成引线框架电子封装关键技术及产业化** |
| **主要完成单位** | 单位 1（佛山市蓝箭电子股份有限公司） |
| 单位 2（西安电子科技大学） |
| 单位3（华南理工大学） |
| **主要完成人****（职称、完成单位、工作单位）** | 1.袁凤江（高级工程师、佛山市蓝箭电子股份有限公司、佛山市蓝箭电子股份有限公司、项目主要完成人） |
| 2.田文超(教授、西安电子科技大学、西安电子科技大学、项目主要完成人） |
| 3.李国元（教授、华南理工大学、华南理工大学、项目主要完成人） |
| 4.张国光（高级工程师、佛山市蓝箭电子股份有限公司、佛山市蓝箭电子股份有限公司、项目主要完成人） |
| 5.陈逸晞(高级工程师、佛山市蓝箭电子股份有限公司、佛山市蓝箭电子股份有限公司、项目主要完成人) |
| 6.雒继军(工程师、佛山市蓝箭电子股份有限公司、佛山市蓝箭电子股份有限公司、项目主要完成人) |
| 7.颜志扬（工程师、佛山市蓝箭电子股份有限公司、佛山市蓝箭电子股份有限公司、项目主要完成人） |
| 10 | 8.麦有海（工程师、佛山市蓝箭电子股份有限公司、佛山市蓝箭电子股份有限公司、项目主要完成人） |
| **代表性论文专著目录** | 论文 1：<铜带缠绕型焊柱装联结构的植柱工艺参数优化、电子与封装、年卷：2021年，第一作者：田文超，通讯作者：田文超> |
| 论文 2：<陶瓷柱栅阵列封装器件回流焊工艺仿真、电子与封装、年卷：2021年、第一作者：田文超，通讯作者：田文超> |
| **知识产权名称** | 专利 1：<SOT23-X引线框架及其封装方法>（专利号：ZL201811317871.0.发明人：[陈逸晞](https://www.baiten.cn/results/l.html?q=in:(%E9%99%88%E9%80%B8%E6%99%9E)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[袁凤江](https://www.baiten.cn/results/l.html?q=in:(%E8%A2%81%E5%87%A4%E6%B1%9F)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[邱焕枢](https://www.baiten.cn/results/l.html?q=in:(%E9%82%B1%E7%84%95%E6%9E%A2)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[王光明](https://www.baiten.cn/results/l.html?q=in:(%E7%8E%8B%E5%85%89%E6%98%8E)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[杨全忠](https://www.baiten.cn/results/l.html?q=in:(%E6%9D%A8%E5%85%A8%E5%BF%A0)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[颜志扬](https://www.baiten.cn/results/l.html?q=in:(%E9%A2%9C%E5%BF%97%E6%89%AC)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)，权利人：佛山市蓝箭电子股份有限公司> |
| 专利 2：<硅芯片封装引线框架及其封装方法>（专利号：ZL201811359648.2.发明人：袁凤江、陈逸晞、徐周、李伟光、陈科、吴晓俊、梁晓峰，权利人：佛山市蓝箭电子股份有限公司> |
| 专利 3：<一种链式交错型微通道结构>（专利号ZL201410816273.3.发明人：田文超，卫三娟，权利人：西安电子科技大学> |
| 专利 4：<一种快速脱模的塑封模具>（专利号：ZL201910880353.8.发明人：[袁凤江](https://www.baiten.cn/results/l.html?q=in:(%E8%A2%81%E5%87%A4%E6%B1%9F)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[麦有海](https://www.baiten.cn/results/l.html?q=in:(%E9%BA%A6%E6%9C%89%E6%B5%B7)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[姚剑锋](https://www.baiten.cn/results/l.html?q=in:(%E5%A7%9A%E5%89%91%E9%94%8B)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[张顺](https://www.baiten.cn/results/l.html?q=in:(%E5%BC%A0%E9%A1%BA)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[张国光](https://www.baiten.cn/results/l.html?q=in:(%E5%BC%A0%E5%9B%BD%E5%85%89)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[邱焕枢](https://www.baiten.cn/results/l.html?q=in:(%E9%82%B1%E7%84%95%E6%9E%A2)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[严向阳](https://www.baiten.cn/results/l.html?q=in:(%E4%B8%A5%E5%90%91%E9%98%B3)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)、[范小宁](https://www.baiten.cn/results/l.html?q=in:(%E8%8C%83%E5%B0%8F%E5%AE%81)" \t "https://www.baiten.cn/results/l/%25E4%25BD%259B%25E5%25B1%25B1%25E5%25B8%2582%25E8%2593%259D%25E7%25AE%25AD%25E7%2594%25B5%25E5%25AD%2590%25E8%2582%25A1%25E4%25BB%25BD%25E6%259C%2589%25E9%2599%2590%25E5%2585%25AC%25E5%258F%25B8/_blank)，权利人：佛山市蓝箭电子股份有限公司> |
| 专利 5：<一种基于薄膜晶体管的模数转换器、芯片以及控制方法 >（专利号：ZL202010504215.2.发明人：范厚波; 陈荣盛; 徐煜明; 吴朝晖; 李斌;李国元，权利人：华南理工大学> |